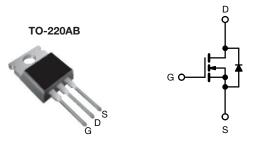
Vishay Siliconix

HALOGEN

FREE

E Series Power MOSFET



N-Channel	MOSEFT

PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	65	50			
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	0.070			
Q _g max. (nC)	6	3			
Q _{gs} (nC)	1	9			
Q _{gd} (nC)	1	0			
Configuration	Sin	gle			

FEATURES

- 4th generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free and halogen-free	SIHP080N60E-GE3

ABSOLUTE MAXIMUM RATINGS (T_{C}	= 25 °C, unl	ess otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V _{DS}	600	V	
Gate-source voltage			V_{GS}	± 30	V	
Continuous drain current (T _J = 150 °C)	V _{GS} at 10 V	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$	I _D	35		
		T _C = 100 °C		22	A	
Pulsed drain current ^a			I _{DM}	96	i	
Linear derating factor				1.8	W/°C	
Single pulse avalanche energy b			E _{AS}	226	mJ	
Maximum power dissipation			P_{D}	227	W	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Drain-source voltage slope		T _J = 125 °C	حاد ، / حالا	100) //	
Reverse diode dv/dt ^d			dv/dt	10	- V/ns	
Soldering recommendations (peak temperature) c	For 10 s			260	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 4.0 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, di/dt = 100 A/ μ s, starting $T_J = 25$ °C



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R_{thJA}	-	62	°C/W	
Maximum junction-to-case (drain)	R _{thJC}	-	0.55	G/ VV	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							•
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	Reference to 25 °C, I _D = 1 mA		0.64	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_D = 250 \mu A$		-	5.0	V
Cata assuma lagicara		V _{GS} = ± 20 V		-	-	± 100	nA
Gate-source leakage	I_{GSS}	,	V _{GS} = ± 30 V		-	± 1	μΑ
Zoro goto voltago drain ourrent	1	V _{DS} =	600 V, V _{GS} = 0 V	-	-	1	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 480 V	V _{DS} = 480 V, V _{GS} = 0 V, T _J = 125 °C		-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 17 A	-	0.070	0.080	Ω
Forward transconductance a	9 _{fs}	V _{DS} = 20 V, I _D = 17 A		-	4.6	-	S
Dynamic							
Input capacitance	C _{iss}	V _{GS} = 0 V,		-	2557	-	pF
Output capacitance	C _{oss}	Ţ ,	$V_{DS} = 100 \text{ V},$		105	-	
Reverse transfer capacitance	C _{rss}	f = 1 MHz		-	6	-	
Effective output capacitance, energy related ^a	$C_{o(er)}$	V _{DS} = 0 V to 480 V, V _{GS} = 0 V		-	79	-	
Effective output capacitance, time related ^b	$C_{o(tr)}$			-	499	-	
Total gate charge	Q_g			-	42	63	
Gate-source charge	Q_{gs}	$V_{GS} = 10 \text{ V}$ $I_D = 17 \text{ A}, V_{DS} = 480 \text{ V}$		-	19	-	nC
Gate-drain charge	Q_gd				10	-	
Turn-on delay time	t _{d(on)}	V_{DD} = 480 V, I_{D} = 17 A, V_{GS} = 10 V, R_{g} = 9.1 Ω		-	31	62	
Rise time	t _r			-	96	144	ne
Turn-off delay time	$t_{d(off)}$			-	37	74	ns
Fall time	t _f			-	31	62	
Gate input resistance	R_{g}	f = 1 MHz, open drain		0.3	0.7	1.4	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	35	
Pulsed diode forward current	I _{SM}			-	-	96	A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 17 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 17 \text{ A},$ $di/dt = 80 \text{ A/µs}, V_R = 25 \text{ V}$		-	441	882	ns
Reverse recovery charge	Q _{rr}			-	5.2	10.4	μC
Reverse recovery current	I _{RRM}			_	21	-	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

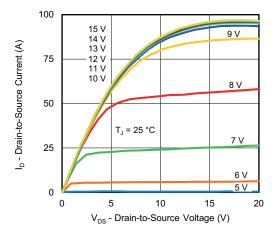


Fig. 1 - Typical Output Characteristics

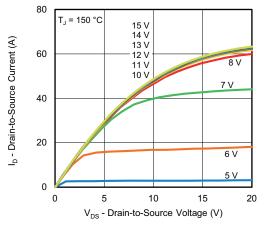


Fig. 2 - Typical Output Characteristics

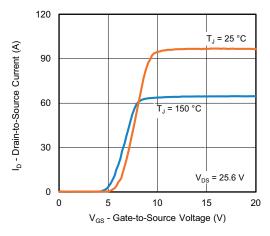


Fig. 3 - Typical Transfer Characteristics

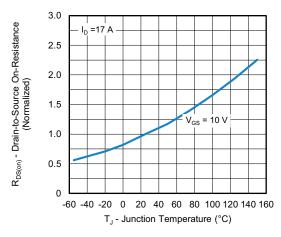


Fig. 4 - Normalized On-Resistance vs. Temperature

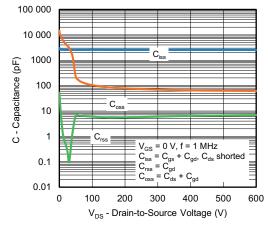


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

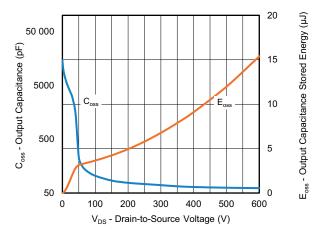


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



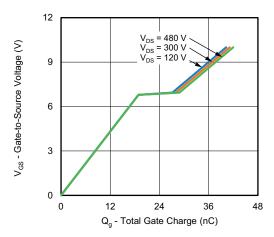


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

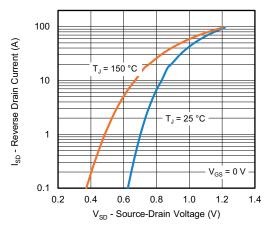


Fig. 8 - Typical Source-Drain Diode Forward Voltage

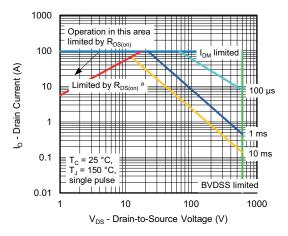


Fig. 9 - Maximum Safe Operating Area



a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

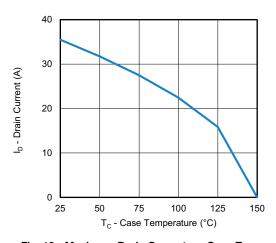


Fig. 10 - Maximum Drain Current vs. Case Temperature

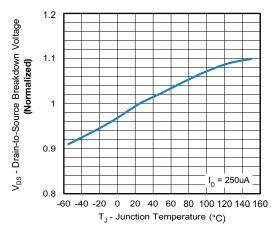


Fig. 11 - Temperature vs. Drain-to-Source Voltage



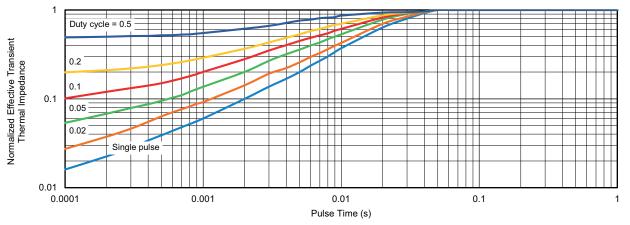


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

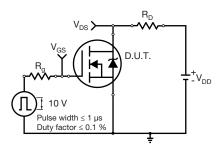


Fig. 13 - Switching Time Test Circuit

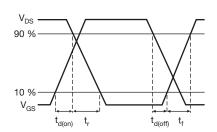


Fig. 14 - Switching Time Waveforms

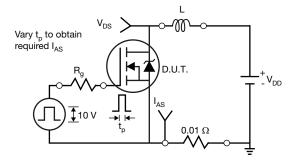


Fig. 15 - Unclamped Inductive Test Circuit

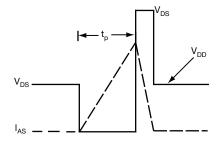


Fig. 16 - Unclamped Inductive Waveforms

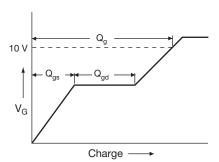


Fig. 17 - Basic Gate Charge Waveform

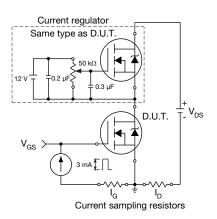
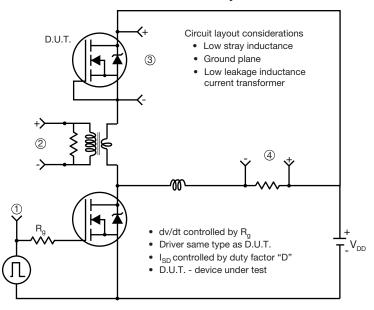


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



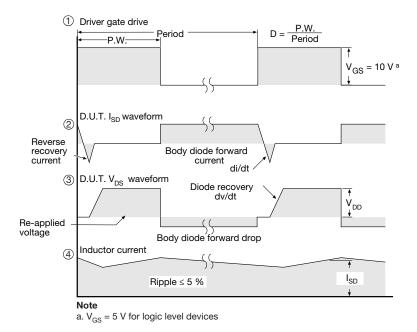


Fig. 19 - For N-Channel

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